

DuPont Electronic Technologies Signs Joint Development Agreement with Taiyo Ink
Collaboration Explores New Material Technologies for Semiconductor Packaging

RESEARCH TRIANGLE PARK, N.C., Oct. 11, 2006 – DuPont Electronic Technologies today announced it has signed a joint development agreement (JDA) with Taiyo Ink Manufacturing Company, Ltd. to advance the development of buildup microvia dry films for use in advanced flip chip ball grid array packages for the semiconductor industry. By combining their interests, expertise and technologies, the companies expect to find new ways to meet the growing demand for higher density circuits with superior interconnect reliability. The early target is a material offering with a low coefficient of thermal expansion (CTE), superior adhesion, improved signal integrity and speed.

“Close collaboration and material integration are critical to meeting our customers’ needs in the semiconductor industry, and key components of our strategy to expand the DuPont offering in this fast growing area of the market,” said David B. Miller, vice president and general manager, DuPont Electronic Technologies. “Combining Taiyo Ink’s proprietary resin technology and expertise with DuPont’s filler, surface treatments and dispersion technologies will result in some exciting new products available for OEM qualification by early next year. Our work with Taiyo Ink is a prime example of the advancements we’re making in developing engineered materials for semiconductor packaging. This market space is also a prime target for DuPont’s embedded passive offerings, where again, integration will be key.”

“Taiyo Ink has established proprietary buildup resin materials and methods to maximize the compatibility of these resins with DuPont filler and dispersion technology,” said Yuichi Kamayachi, president and chief executive officer, Taiyo Ink Manufacturing Company, Ltd. “We feel this is a strong partnership that will benefit our customers and the industry.”

DuPont Electronic Technologies is a leading supplier of electronic materials, including materials for the fabrication and packaging of semiconductors, materials for rigid and flexible circuits, and materials for advanced displays. For more information on DuPont Electronic Technologies, please visit electronics.dupont.com.

DuPont is a science company. Founded in 1802, DuPont puts science to work by creating sustainable solutions essential to a better, safer, healthier life for people everywhere. Operating in more than 70 countries, DuPont offers a wide range of innovative products and services for markets including agriculture, nutrition, electronics, communications, safety and protection, home and construction, transportation and apparel.

Forward-Looking Statements: This news release contains forward-looking statements based on management's current expectations, estimates and projections. All statements that address expectations or projections about the future, including statements about the company's strategy for growth, product development, market position, expected expenditures and financial results are forward-looking statements. Some of the forward-looking statements may be identified by words like "expects," "anticipates," "plans," "intends," "projects," "indicates," and similar expressions. These statements are not guarantees of future performance and involve a number of risks, uncertainties and assumptions. Many factors, including those discussed more fully elsewhere in this release and in DuPont's filings with the Securities and Exchange Commission, particularly its latest annual report on Form 10-K, as well as others, could cause results to differ materially from those stated. These factors include, but are not limited to changes in the laws, regulations, policies and economic conditions of countries in which the company does business; competitive pressures; successful integration of structural changes, including acquisitions, divestitures and alliances; research and development of new products, including regulatory approval and market acceptance, and seasonality of sales of agricultural products.

#

10/11/06

Emily Bezek
Senior Account Executive
Ogilvy Public Relations Worldwide
1111 19th Street NW
10th Floor
Washington, DC 20036
202 729-4000
202 729-4246 direct
202 729-4001 fax
emily.bezek@ogilvypr.com